

Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification
- Fast reverse recovery

$$V_{DSS} = 660 \text{ V @ } T_{jmax}$$

$$I_D = 9 \text{ A}$$

$$R_{DS(ON)} = 1.0 \text{ (max) @ } V_{GS} = 10 \text{ V}$$

Absolute Maximum Ratings

Parameter	Symbol	TMP9N60(G)	TMPF9N60(G)	Unit	
Drain-Source Voltage	V_{DSS}	600		V	
Gate-Source Voltage	V_{GS}	±30		V	
Continuous Drain Current	I_D	$T_C = 25 \text{ }^\circ\text{C}$	9	9 *	A
		$T_C = 100 \text{ }^\circ\text{C}$	5	5 *	A
Pulsed Drain Current (Note 1)	I_{DM}	44	44*	A	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	662		mJ	
Repetitive Avalanche Current (Note 1)	I_{AR}	9		A	
Repetitive Avalanche Energy (Note 1)	E_{AR}	15.8		mJ	
Power Dissipation	P_D	$T_C = 25 \text{ }^\circ\text{C}$	158	51.4	W
		Derate above 25 °C	1.26	0.41	W/°C
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150		°C	
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	300		°C	

Thermal Characteristics

Electrical Characteristics : $T_C=25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min	Typ	Max	Units
OFF						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	600	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 480\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
Forward Gate-Source Leakage Current	I_{GSSF}	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
Reverse Gate-Source Leakage Current	I_{GSSR}	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

ON

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2	--	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 4.5\text{ A}$	--	0.83	1.0	
Forward Transconductance ^(Note 4)	g_{FS}	$V_{DS} = 30\text{ V}, I_D = 4.5\text{ A}$	--	10	--	S

DYNAMIC

Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	1440	--	pF
Output Capacitance	C_{oss}		--	123	--	pF
Reverse Transfer Capacitance	C_{rss}		--	8.1	--	pF

SWITCHING

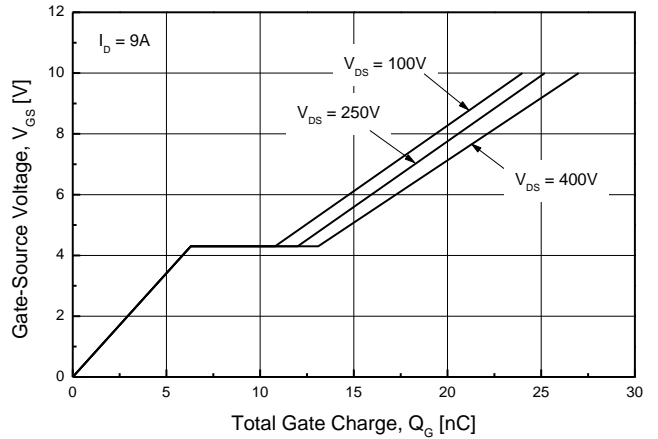
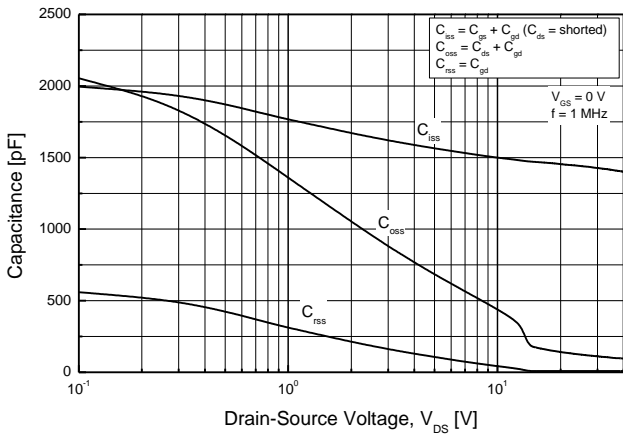
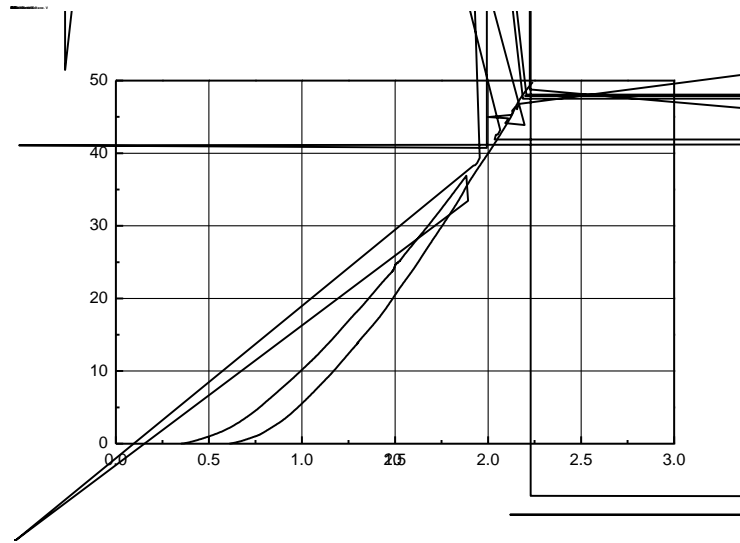
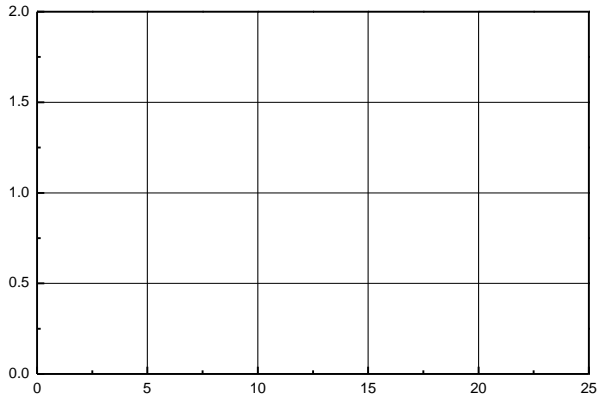
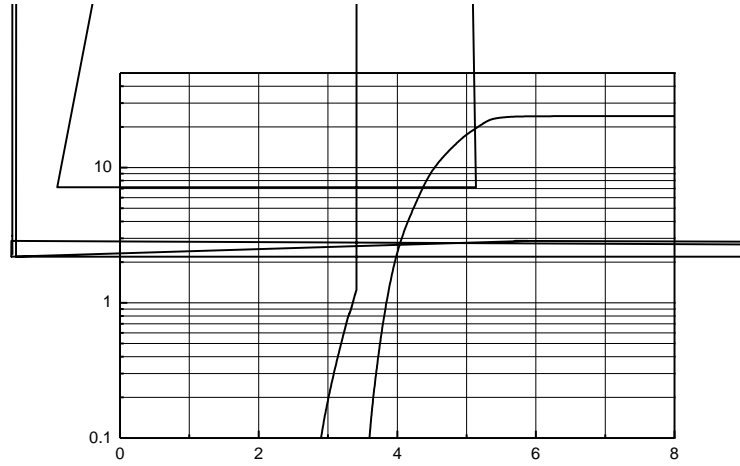
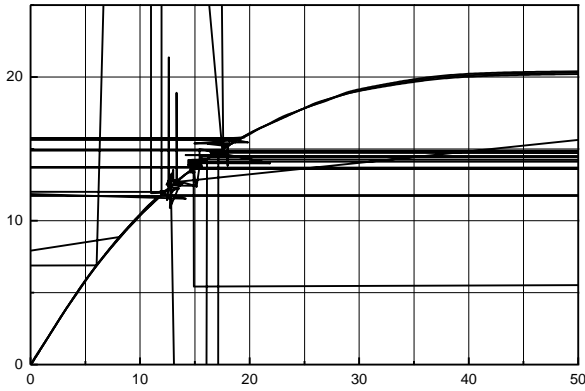
Turn-On Delay Time ^(Note 4,5)	$t_{d(on)}$	$V_{DD} = 250\text{ V}, I_D = 9\text{ A},$ $R_G = 25$	--	50	--	ns
Turn-On Rise Time ^(Note 4,5)	t_r		--	39	--	ns
Turn-Off Delay Time ^(Note 4,5)	$t_{d(off)}$		--	133	--	ns
Turn-Off Fall Time ^(Note 4,5)	t_f		--	532	--	ns
Total Gate Charge ^(Note 4,5)	Q_g	$V_{DS} = 400\text{ V}, I_D = 9\text{ A},$ $V_{GS} = 10\text{ V}$	--	27	--	nC
Gate-Source Charge ^(Note 4,5)	Q_{gs}		--	6.3	--	nC
Gate-Drain Charge ^(Note 4,5)	Q_{gd}		--	6.9	--	nC

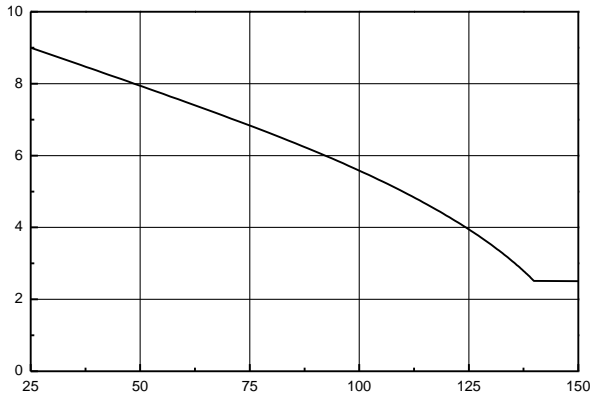
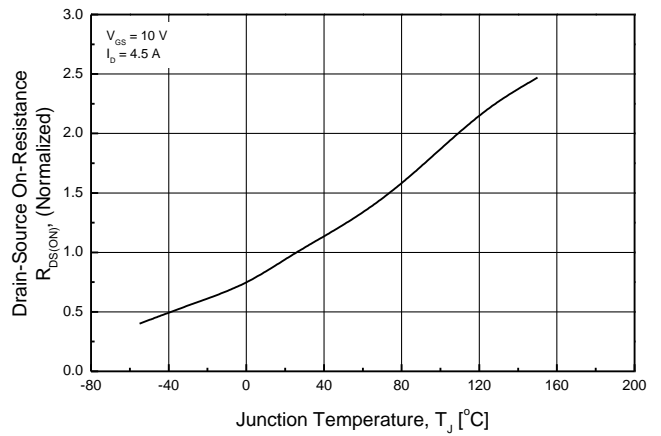
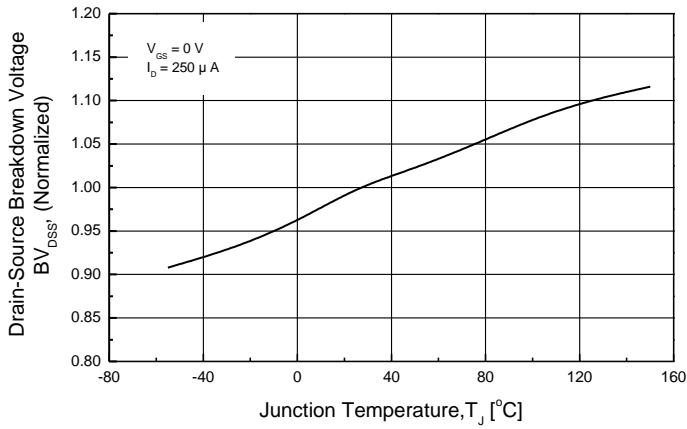
SOURCE DRAIN DIODE

Maximum Continuous Drain-Source Diode Forward Current	I_S	----	--	--	9	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}	----	--	--	36	A
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = 9\text{ A}$	--	--	1.5	V
Reverse Recovery Time ^(Note 4)	t_{rr}	$V_{GS} = 0\text{ V}, I_S = 9\text{ A}$	--	350	--	ns
Reverse Recovery Charge ^(Note 4)	Q_{rr}	$di_F / dt = 100\text{ A}/\mu\text{s}$	--	3.2	--	C

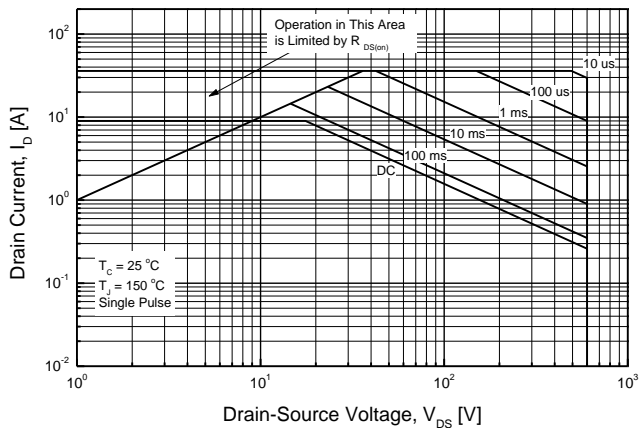
Note :

1. Repeated rating : Pulse width limited by safe operating area
2. $L=15\text{mH}, I_{AS} = 9\text{ A}, V_{DD} = 50\text{ V}, R_G = 25$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} = 9\text{ A}, di/dt = 200\text{ A}/\mu\text{s}, V_{DD} = BV_{DS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $300\ \mu\text{s}$, Duty Cycle 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

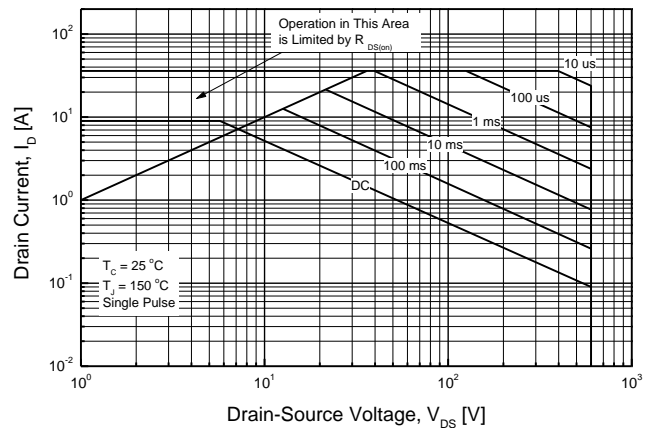




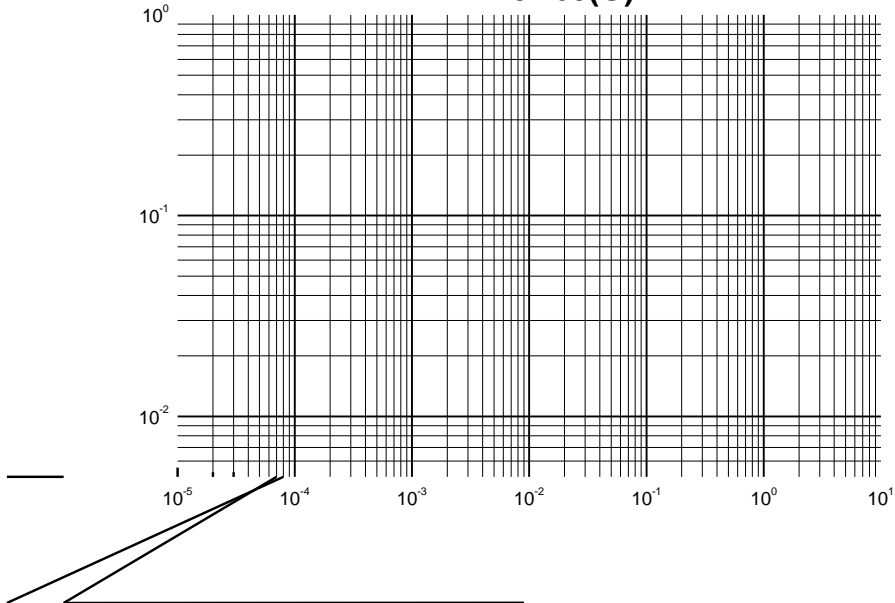
TMP9N60(G)



TMPF9N60(G)



TMP9N60(G)



TMPF9N60(G)

